# 2017-10-30 Rev.1.0

**TOSHIBA** 

RD Number: RD050

RD Title: TC78B016FTG Evaluation circuit

Item								
		Quantity	Value	·		Description	Package	Not Mount
1	IC1	1	-	TC78B016FTG	Toshba			
2	R1	1	27 kΩ					
3	R3	1	10 kΩ					
4	R4	1	10 kΩ					
5	R5	1	-					
6	R6	1	-					
7	R9	1	-					
8	R10	1	-					
9	R17	1	-					
10	R18	1	-					
11	R21	1	-					
12	R22	1	-					
13	R23	1	-					
14	R24	1	-					
15	R25	1	-					
	R26	1	-					
17	R27	1	-					
18	R28	1	-					
	R29	1	-					
20	R30	1	-					
	R31	1	-					
	R32	1	-					
	R33	1	0.1 Ω					
	R36	1	-					
	R37	1	-					
	R38	1						

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27		-			
28		360 pF			
29	C2 1	0.1 μF			
30	C3 1	0.01 μF			
31	C4 1	0.01 μF			
32	C5 <sub>1</sub>	0.01 μF			
33	C6 <sub>1</sub>	0.01 μF			
34	C7 1	0.1 μF			
35	C8 1	10 μF/50 V			
36	C10 1	-			
37	C11 1	-			
38	C15 <sub>1</sub>	-			
39	C17 1	-			
40	C18 1	-			
41	C21 1	-			
42	C22 1	-			
43	C23	-			
44	C24	-			
45	C25	-			
46	C26	-			
47	JP1	Short			
48	JP2	Short			
49	JP3	-			
50	JP4	-			
51		-			
52	JP6	-			
53	JP7	-			
54		Short			
55	JP9	-			
	JP10	-			
57	JP11	-			
58	JP12	Short			
59	JP13	Short			
60	JP14	-			

61 <sup>3</sup>		-			
62 <sup>J</sup>	JP16	-			
63 <sup>J</sup>	JP19	Short			
64	SW1	SW			
65	SW2	SW			
66	SW3	SW			
67	5W4	SW			
68	SW5	SW			
69 \	VR2	VR (50 kΩ)			
70 \	VR3	VR (50 kΩ)			
71	VR4	VR (50 kΩ)			
72					
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